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- Output Ports Have Equivalent 25-Ω Series Resistors So No External Resistors Are Required
- Members of the Texas Instruments Widebus™ Family
- State-of-the-Art EPIC-IIB™ BiCMOS Design Significantly Reduces Power Dissipation
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Typical V<sub>OLP</sub> (Output Ground Bounce) < 1 V at V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C
- Distributed V<sub>CC</sub> and GND Pin Configuration Minimizes High-Speed Switching Noise
- Flow-Through Architecture Optimizes PCB Layout
- Package Options Include Plastic 300-mil Shrink Small-Outline (DL) Package and 380-mil Fine-Pitch Ceramic Flat (WD) Package Using 25-mil Center-to-Center Spacings

### description

These 18-bit bus-interface flip-flops feature 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. They are particularly suitable for implementing wider buffer registers, I/O ports, bidirectional bus drivers with parity, and working registers.

The 'ABT162823 can be used as two 9-bit flip-flops or one 18-bit flip-flop. With the clock-enable ( $\overline{\text{CLKEN}}$ ) input low, the D-type flip-flops enter data on the low-to-high transitions of the clock. Taking  $\overline{\text{CLKEN}}$  high disables the clock buffer, thus latching the outputs. Taking the clear ( $\overline{\text{CLR}}$ ) input low causes the Q outputs to go low independently of the clock.

SN54ABT162823 . . . WD PACKAGE SN74ABT162823 . . . DL PACKAGE (TOP VIEW)

		Т		
1CLR	1	$\cup$	56	]1CLK
1 <u>0E</u> [	2		55	1CLKEN
1Q1 [	3		54	] 1D1
GND [	4		53	GND
1Q2 [	5		52	] 1D2
1Q3 [	6		51	] 1D3
v <sub>cc</sub> [			50	
1Q4 [	8			] 1D4
1Q5 [	9			] 1D5
1Q6 [	10			] 1D6
GND [	11			GND
1Q7 [			45	] 1D7
1Q8 [	13			] 1D8
1Q9 [	14		43	] 1D9
2Q1 [	15		42	2D1
2Q2 [	16		41	2D2
2Q3 [			40	2D3
GND [	18		39	GND
2Q4 [	19		38	] 2D4
2Q5 [	20		37	] 2D5
2Q6 [	21		36	] 2D6
V <sub>CC</sub> [	22		35	]v <sub>cc</sub>
2Q7 [	23		34	] 2D7
2Q8 [	24		33	2D8
GND [	25		32	GND
2Q9	26		31	2 <u>D9</u>
20E [	27		30	2CLKEN
2CLR	28		29	]2CLK

A buffered output-enable (OE) input places the nine outputs in either a normal logic state (high or low logic level) or a high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without interface or pullup components. OE does not affect the internal operation of the flip-flops. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

The outputs, which are designed to source or sink up to 12 mA, include equivalent 25- $\Omega$  series resistors to reduce overshoot and undershoot.



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## SN54ABT162823, SN74ABT162823 18-BIT BUS-INTERFACE FLIP-FLOPS WITH 3-STATE OUTPUTS

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## description (continued)

To ensure the high-impedance state during power up or power down,  $\overline{\text{OE}}$  should be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

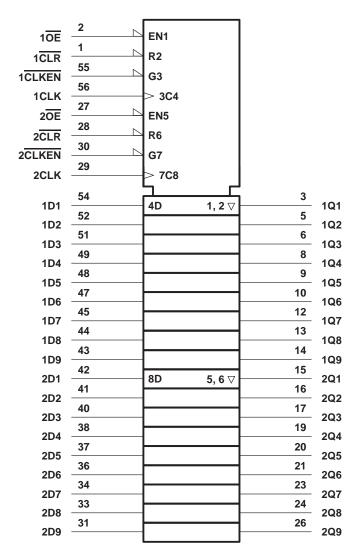
The SN54ABT162823 is characterized for operation over the full military temperature range of  $-55^{\circ}$ C to  $125^{\circ}$ C. The SN74ABT162823 is characterized for operation from  $-40^{\circ}$ C to  $85^{\circ}$ C.

FUNCTION TABLE (each 9-bit flip-flop)

		•		1,	
		INPUTS			OUTPUT
OE	CLR	CLKEN	CLK	D	Q
L	L	Х	Χ	Х	L
L	Н	L	$\uparrow$	Н	Н
L	Н	L	$\uparrow$	L	L
L	Н	L	L	Х	Q <sub>0</sub>
L	Н	Н	Χ	Χ	Q <sub>0</sub>
Н	Χ	X	Χ	Χ	Z



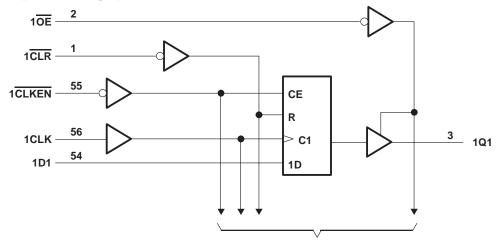
# logic symbol†



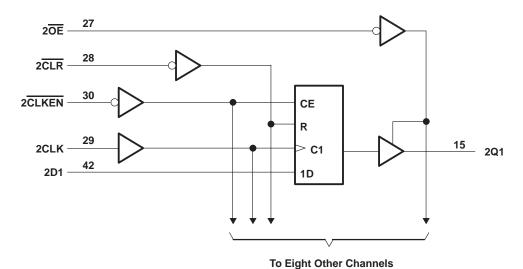
<sup>&</sup>lt;sup>†</sup> This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

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### logic diagram (positive logic)



To Eight Other Channels



## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage range, V <sub>CC</sub>	0.5 V to 7 V
Input voltage range, V <sub>I</sub> (see Note 1)	0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, VO	0.5 V to 5.5 V
Current into any output in the low state, IO	30 mA
Input clamp current, $I_{ K }(V_{ } < 0)$	
Output clamp current, I <sub>OK</sub> (V <sub>O</sub> < 0)	−50 mA
Package thermal impedance, θ <sub>JA</sub> (see Note 2): DL package	74°C/W
Storage temperature range, T <sub>stq</sub>	65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51.



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## recommended operating conditions (see Note 3)

			SN54ABT	162823	SN74ABT	162823	UNIT
			MIN	MAX	MIN	MAX	UNIT
Vсс	Supply voltage		4.5	5.5	4.5	5.5	V
VIH	High-level input voltage	2	FIN	2		V	
V <sub>IL</sub>	Low-level input voltage		0.8		8.0	V	
VI	Input voltage		0 0	Vcc	0	Vcc	V
IOH	High-level output current		Ç	-12		-12	mA
loL	Low-level output current			12		12	mA
Δt/Δν	Input transition rise or fall rate	Outputs enabled	B	10		10	ns/V
TA	Operating free-air temperature		-55	125	-40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETER	TEST CONDITIONS		T <sub>A</sub> = 25°C			SN54ABT162823		SN74ABT162823			
PARAMETER			MIN	TYP <sup>†</sup>	MAX	MIN	MAX	MIN	MAX	UNIT	
VIK	$V_{CC} = 4.5 \text{ V},$	I <sub>I</sub> = -18 mA				-1.2		-1.2		-1.2	V
	$V_{CC} = 4.5 \text{ V},$	I <sub>OH</sub> = -1 mA	١	3.35			3.35		3.35		
Vari	$V_{CC} = 5 V$ ,	$I_{OH} = -1 \text{ m/s}$	١	3.85			3.85		3.85		V
VOH	V <sub>CC</sub> = 4.5 V	$I_{OH} = -3 \text{ m/s}$	\	3.1			3.1		3.1		V
	VCC = 4.5 V	$I_{OH} = -12 \text{ m}$	Α	2.6*					2.6		
VOL	V <sub>CC</sub> = 4.5 V	$I_{OL} = 8 \text{ mA}$			0.4	0.8		0.8		0.65	V
VOL	VCC = 4.5 V							F		8.0	٧
V <sub>hys</sub>					100			W			mV
ΙĮ	$V_{CC} = 5.5 \text{ V},$	$V_{CC} = 5.5 \text{ V},  V_I = V_{CC} \text{ or GND}$				±1	· Q	±1		±1	μΑ
lozh	$V_{CC} = 5.5 \text{ V},$	$_{CC} = 5.5 \text{ V},  V_{O} = 2.7 \text{ V}$				10	(0)	10		10	μΑ
lozL	$V_{CC} = 5.5 \text{ V},$	$V_0 = 0.5 V$				-10	200	-10		-10	μΑ
l <sub>off</sub>	$V_{CC} = 0$ ,	$V_I$ or $V_O \le 4$ .	5 V			±100	940			±100	μΑ
ICEX	$V_{CC} = 5.5 \text{ V},$	$V_0 = 5.5 V$	Outputs high			50		50		50	μΑ
1 <sub>0</sub> ‡	$V_{CC} = 5.5 \text{ V},$	$V_0 = 2.5 V$		-25	-55	-100	-25	-100	-25	-100	mA
		0	Outputs high			2		2		2	
Icc	$V_{CC} = 5.5 \text{ V}, \text{ I}_{C}$ $V_{I} = V_{CC} \text{ or G}$		Outputs low			80		80		80	mA
	VI = VCC OI GIVD		Outputs disabled			2		2		2	
ΔlCC§	$V_{CC}$ = 5.5 V, One input at 3.4 V, Other inputs at $V_{CC}$ or GND				1.5		1.5		1.5	mA	
Ci	$V_{I} = 2.5 \text{ V or } 0.$	.5 V			3						pF
Co	$V_0 = 2.5 \text{ V or } 0$	0.5 V			8						pF

<sup>\*</sup> On products compliant to MIL-PRF-38535, this parameter does not apply.



<sup>&</sup>lt;sup>†</sup> All typical values are at  $V_{CC} = 5 \text{ V}$ .

<sup>‡</sup> Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

<sup>§</sup> This is the increase in supply current for each input that is at the specified TTL-voltage level rather than VCC or GND.

## SN54ABT162823, SN74ABT162823 18-BIT BUS-INTERFACE FLIP-FLOPS WITH 3-STATE OUTPUTS

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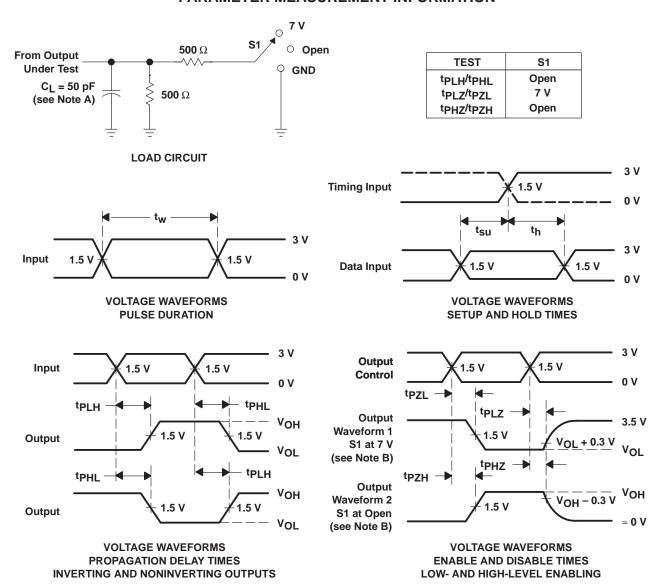
# timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

			V <sub>CC</sub> = 5 V, T <sub>A</sub> = 25°C		SN54ABT162823		SN74ABT162823		UNIT	
			MIN	MAX	MIN	MAX	MIN	MAX		
fclock	Clock frequency		0	150	0	150	0	150	MHz	
	Pulse duration	CLR low	3.3		3.3	N <sub>2</sub>	3.3		ns	
t <sub>W</sub>	Pulse duration	CLK high or low	3.3		3.3	7.	3.3			
		CLR inactive	1.6		2 2	Q-7 2	1.6			
t <sub>su</sub>	Setup time before CLK↑	Data	1.7		1.7		1.7		ns	
		CLKEN low	2.8		2.8		2.8			
th F		Data	1.2		29.2		1.2			
	Hold time after CLK↑	CLKEN low	0.6		0.6		0.6		ns	

# switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L = 50$ pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)		V <sub>CC</sub> = 5 V, T <sub>A</sub> = 25°C		SN54ABT162823		SN74ABT162823		UNIT	
	(INFOT)	(001F01)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f <sub>max</sub>			150			150	4	150		MHz
t <sub>PLH</sub>	CLK	Q	2.3	4.6	6.2	2.3	8.4	2.3	7.5	ns
<sup>t</sup> PHL	CLK	ά	2.8	4.6	6.1	2.8	7.1	2.8	6.7	115
t <sub>PHL</sub>	CLR	Q	2.8	5	6.2	2.8	7.2	2.8	7	ns
<sup>t</sup> PZH	ŌĒ	Q	1.7	3.8	4.9	1,7	5.8	1.7	5.6	no
t <sub>PZL</sub>	OE OE	ď	3	5	6.1	3	7.2	3	7	ns
<sup>t</sup> PHZ	ŌĒ	Q	2.7	4.8	6.1	2.7	7.3	2.7	6.6	ne
t <sub>PLZ</sub>	OE OE	γ	1.9	4.6	6.7	1.9	10.2	1.9	9	ns

### PARAMETER MEASUREMENT INFORMATION



NOTES: A. C<sub>I</sub> includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_O = 50 \ \Omega$ ,  $t_f \leq 2.5 \ ns$ ,  $t_f \leq 2.5 \ ns$ .
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms





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#### **PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
SN74ABT162823DGGR	OBSOLETE			56	TBD	Call TI	Call TI
SN74ABT162823DL	OBSOLETE	SSOP	DL	56	TBD	Call TI	Call TI
SN74ABT162823DLR	OBSOLETE	SSOP	DL	56	TBD	Call TI	Call TI

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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